

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
SHAO-CHI YU	03/13/2015
CHIA-MING HUNG	03/13/2015
HSIN-TING HUANG	03/13/2015
HSIANG-FU CHEN	03/13/2015
ALLEN TIMOTHY CHANG	03/13/2015
WEN-CHUAN TAI	03/13/2015
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<b>Postal Code:</b>	300-77
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	14645826
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<b>ATTORNEY DOCKET NUMBER:</b>	TSMCP541US
<b>NAME OF SUBMITTER:</b>	DAVID W. POTASHNIK
<b>SIGNATURE:</b>	/David W. Potashnik/
<b>DATE SIGNED:</b>	03/24/2015

PATENT

**Total Attachments: 8**

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PATENT ASSIGNMENT

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**AGREEMENT**

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled  
**“MONOLITHIC MEMS PLATFORM FOR INTEGRATED PRESSURE,  
TEMPERATURE, AND GAS SENSOR”** for which:

a non-provisional application for United States Letters Patent:

was executed on even date preparatory to filing (each inventor should sign this  
Assignment on the same day as he/she signs the Declaration); or

was filed on \_\_\_\_\_ and accorded U.S. Serial No. \_\_\_\_\_; or

I hereby authorize and request my attorney associated with Customer No.  
107476, to insert on the designated lines below the filing date and application  
number of said application when known:

U.S. Serial No. \_\_\_\_\_,

filed on \_\_\_\_\_.

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is  
desirous of acquiring the entire right, title and interest in and to the invention and in and to  
any letters patent that may be granted therefore in the United States and in any and all  
foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of  
which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto  
ASSIGNEE its successors and assigns, the entire right, title and interest in and to said  
invention and improvements, said application and any and all letters patent which may be  
granted for said invention in the United States of America and its territorial possessions and  
in any and all foreign countries, and in any and all divisions, reissues, re-examinations and  
continuations thereof, including the right to file foreign applications directly in the name of  
ASSIGNEE and to claim priority rights deriving from said United States application to which

said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

2015/3/13  
Date

Shao-Chi Yu  
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2015/3/13  
Date

Chia-Ming Hung  
Name 2<sup>nd</sup> Inventor Chia-Ming Hung

TSMC Docket No. P20150019US00  
Docket No. TSMCP541US

2015.3.13  
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2015.3.13  
Date

Hsiang-Fu Chen  
Name 4<sup>th</sup> Inventor Hsiang-Fu Chen



TSMC Docket No. P20150019US00  
Docket No. TSMCP541US

March 13, 2015  
Date

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Name 5<sup>th</sup> Inventor Allen Timothy Chang

2015 / 3 / 13  
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